

Innovating MEMS and Sensor Packaging for Limitless Applications

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With MEMS technology and applications recognized as key components in automotive, consumer electronics, mobile communications, and industrial and medical products, there has been additional pressure on packaging and test, creating challenges to achieve the highest possible performance when responding and interacting with any external or environmental stimuli.

Hear from Dr. Huang how ASE and others are enabling technology breakthroughs that are literally changing lives, from robotics to AI, from edge to cloud, from health to transportation, and from 5G to beyond.